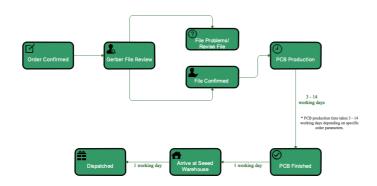


Fusion PCB Specification

← Fusion Specification

New and returning users may sign in

PCB Order Flow Chart



PCB Gerber

The Gerber format is an open 2D binary vector image file format. It is the standard file used by printed circuit board (PCB) industry software to describe the printed circuit board images: copper layers, solder mask, legend, etc.

Gerber files should be inside a .rar or.zip archive with standard file extensions:

Extension	Layer
 pcbname.GTL pcbname.GTS pcbname.GTO pcbname.GBL pcbname.GBS pcbname.GBO pcbname.TXT pcbname.GML/GKO pcbname.GL2 pcbname.GL3 	Top Copper Top Soldermask Top Silkscreen Bottom copper Bottom Soldermask: Bottom Silkscreen: Drills Board Outline Inner Layer2(for ≥4 layer) Inner Layer3(for ≥4 layer)
poblicatio. OLO	111101 Layoro(101 =+ layor)

Notes:

- 1. Gerber file must be the RS-274x format
- 2. Drill file(PCBname.TXT) should be Excellon format

Fusion Specification Fusion PCB Specification Fusion PCBA Specification Fusion PCB Stencil Specification Fusion Aluminum PCB Specification Fusion FPC (Flexible PCB) Specification Fusion Advanced PCB Specification Fusion Shipment Specification

Fusion Reference Data



3. Gerber file and Drill file(PCB name.TXT) must be put in the same folder

4. Board outline is required

標準規格書(Fusion向け) 9 All articles



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■ PCB Specification for FR4-TG130

Items	Description	Specs
		Unit: mm
Board Dimension	Min size	10mm*10mm Tip: If your board width is smaller than this size, you can make a bigger panel and use slots to separate the board.
	Max size	500*500mm
Available Board Layers	1-6 layers	
Available Board Qty	Min: 5pcs	
	Max: 8000pcs	
Dielectric Constant	4.2-4.7	
Dielectric Separation thickness		0.075 - 5.0
	1-2 layers	0.6, 0.8, 1, 1.2, 1.6, 2, 2.5, 3
Available Board Thickness	4 layers	0.8, 1, 1.2, 1.6, 2, 2.5, 3
	6-8 layers	1, 1.2, 1.6, 2, 2.5, 3
	10 layers	1.2, 1.6, 2, 2.5, 3
	12 layers	1.6, 2, 2.5, 3
	14 layers	2, 2.5, 3
	16 layers	2.5,3
Available Board Copper Weigh	1oz. 2oz. 3oz.	
Board Thickness Tolerance	± 10%	
Minimum trace spacing / width	Minimum Spacing Amil	For 1oz, 4/4mil, 5/5mil, 6/6mil For 2oz, 10/10mil For 3oz, 15/15mil

5/2019	Fusion PCB Spe	cification – Feedi	oack & Ideas for seeed
	Minim	um Width 4mil	
Minimum trace width in inner layers (for 4 layers board)	1	Minimum Spacing um Fidth	≥6mil
Minimum distance between trace and pour	d copper		For 1oz ≥ 8mil For 2oz ≥ 12mil For 3oz ≥ 15mi
Minimum distance between vias (plat	ted holes)	>12mil	≥12mil Aim to prevent lon migration
Minimum distance between via(plater and trace	d holes)	>12mil	≥12mil Aim to prevent lon migration
Annular Rings			≥0.152mm/6mil
Outer Layer Copper Thickness		Top Layer : 102-0.035es Leyer 2 Layer 3 Botton Lauer : 102-0.035es	0.035-0.07(1oz-2oz)
Inner Layer Copper Thickness		Top Layer Layer 2: 0.50z/0.017em Layer 3: 0.50z/0.017em Botton Layer	0.017(0.5oz)
Drilling Hole Diameter(Mechanical)			0.2 - 6.3mm
Width of Solder Mask Dam			Normal: ≥0.32mm for Green ≥0.35mm for Other colors Limitation(need extra fee): ≥0.10mm for Green ≥0.13mm for Other colors
Diameter of Castellated Holes			≥0.50mm

Size of BGA		For 6/6mil ≥0.45mm For 5/5mil ≥0.35mm For 4/4mil ≥0.25mm
Circuit to edge		≥0.3mm
Minimum distance between inner trace and non-plated hole	100 To 100	≥0.2mm/7.87mil
Minimum silkscreen height/trace width	Min Height Min trace width	height ≥0.5842mm /23mil trace width ≥0.1016mm /4mil
Perfect aspect ratio of silkscreen		1: 5
Silkscreen colour		Silkscreen colour is WHITE when solder mask is Green, Red, Yellow, Blue, Black Silkscreen colour is BLACK when solder mask is white
Minimum distance between pad and silkscreen	No. 1. F. 1. No.	≥0.1524mm/6mil
Minimum milling slot width		≥0.8mm
Slot Tolerance(Mechanical)		±0.15mm
The minimum board dimension of V-CUT	The V out line	≥70*55mm
The maximum board dimension of V-CUT	The V-cut line only is cut from edge to edge	≤380*380mm
The minimum sub-board dimension of V-CUT		≥8*8mm
		3-14 working days

PCB production time(build time)

* PCB production time takes 3 - 14 working days depending on specific order parameters.

Aluminum Board Specification	
Layer:	1
Available Board Thickness:	1mm, 1.2mm, 1.6mm, 2mm
QTY	min: 5, max: 8000
Board Dimension:	min: 10mm*10mm
	max: 500*500mm
Available Board Colour:	White (Silkscreen is black)
	Black (Silkscreen is white)
Copper weight:	1oz
Surface Finish:	HASL, HASL lead-free, ENIG, OSP, Hard Gold
Minimum Trace Width:	4mil
Minimum Trace Spacing:	4mil
Minimum Drilling Hole:	0.2mm
Production Lead Time:	5-11 business days

FPC Board Specification	
Layer:	1, 2
Available Board Thickness:	0.1mm,0.15mm
QTY within:	min:5,max:8000
Board Dimension:	max:100mm*100mm
Available Board Colour:	Yellow
Silkscreen:	White
Copper weight:	0.5oz

Surface Finish:	ENIG
Minimum Trace Width:	0.10mm
Minimum Trace Spacing:	0.10mm
Minimum Drilling Hole:	0.3mm
Production Lead Time:	5-7 working days
The temperature of FPC	Low-temperature resistance: -40°C High-temperature resistance: 280°C

Panelization Rules:

Please <u>click here</u> for more details.

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